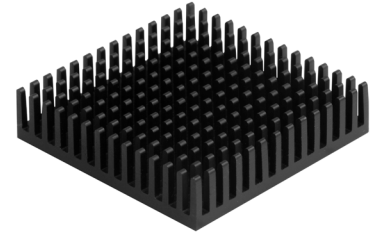


MODEL: HSB26-343408 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- top mount
- aluminum alloy



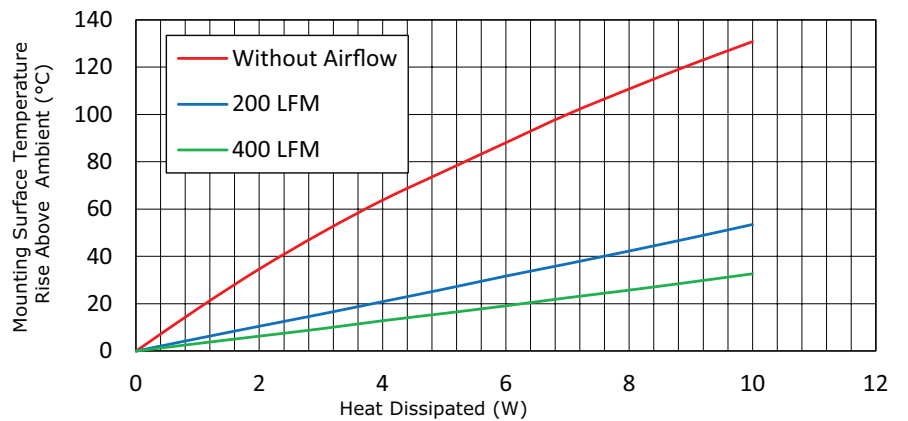
MODEL

	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB26-343408	15.19	17.9	5.3	3.2	4.94

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	17.9	5.3	3.2
2	34.7	10.5	6.3
3	49.9	15.6	9.4
4	63.8	20.9	12.8
5	76.0	26.2	15.9
6	88.1	31.7	19.1
7	100.1	36.9	22.5
8	110.8	42.3	25.7
9	121.1	47.8	29.1
10	130.8	53.5	32.6

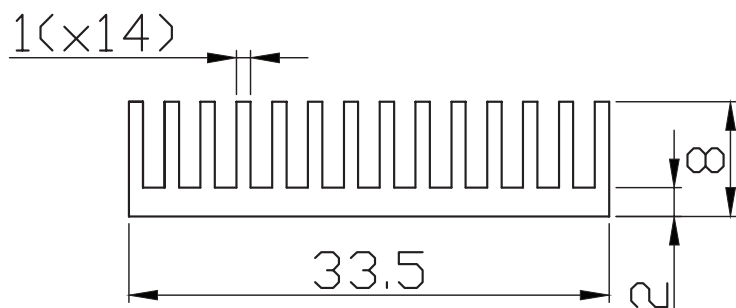
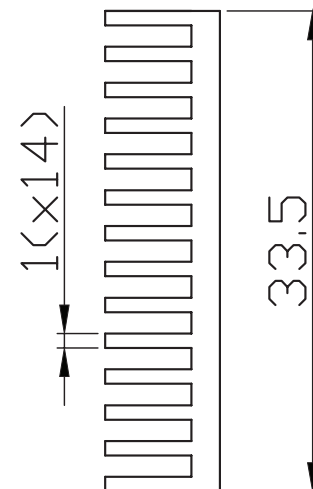
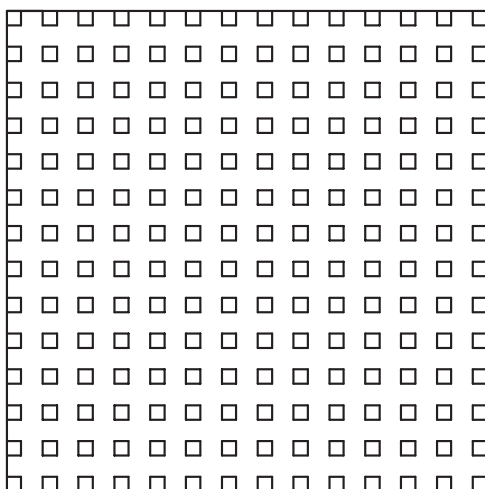


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	15.6 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/15/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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